

PRELIMINARY DATA SHEET

NEC

Solid State Relay
OCMOS FET

PS7801D-1A

**4-PIN ULTRA SMALL FLAT-LEAD,
LOW OUTPUT CAPACITANCE (0.6 pF), 1-ch Optical Coupled MOS FET**

DESCRIPTION

The PS7801D-1A is a low output capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 50% compared with the PS72xx series.

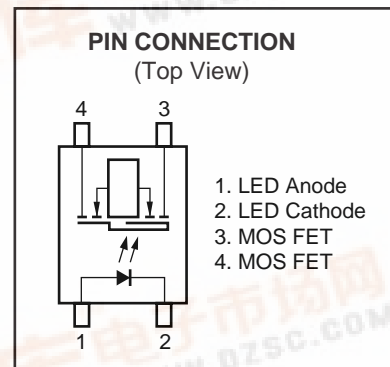
It is suitable for high-frequency signal control, due to its low $C \times R$, low output capacitance, and low off-state leakage current.

FEATURES

- Ultra small flat-lead package (4.2 (L) × 2.5 (W) × 1.85 (H) mm)
- Low $C \times R$ ($C \times R = 6.6 \text{ pF} \cdot \Omega$)
- Low output capacitance ($C_{out} = 0.57 \text{ pF TYP.}$)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Low offset voltage
- Ordering number of taping product: PS7801D-1A-F3, F4 (3 500 pcs/reel)
- Pb-Free product
- UL awaiting approval

APPLICATIONS

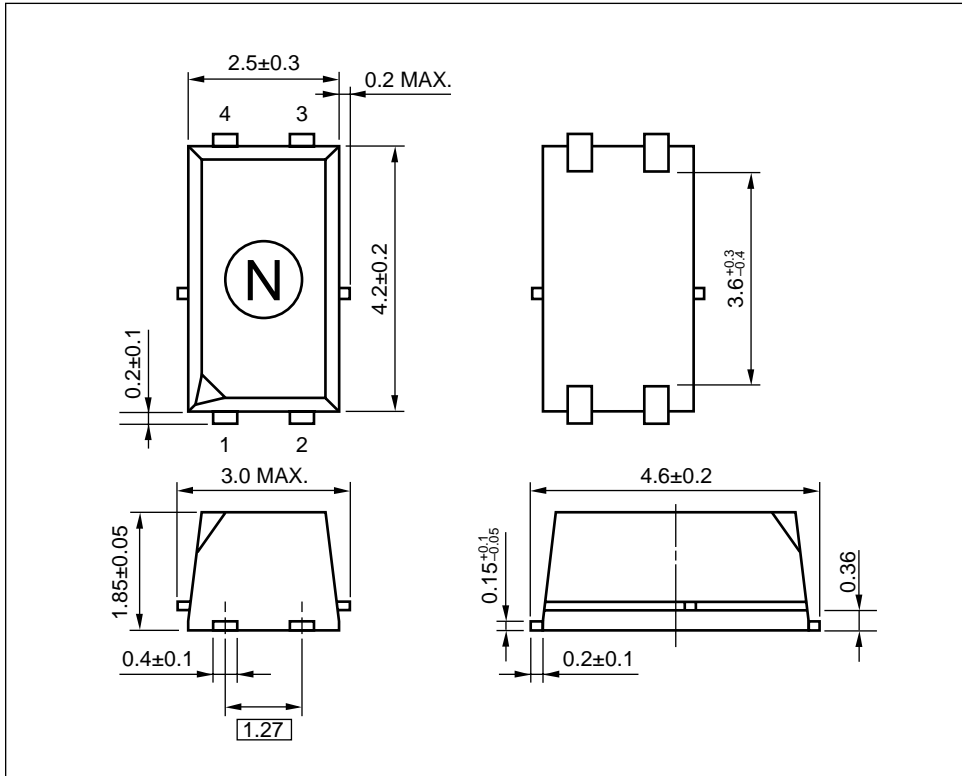
- Measurement equipment



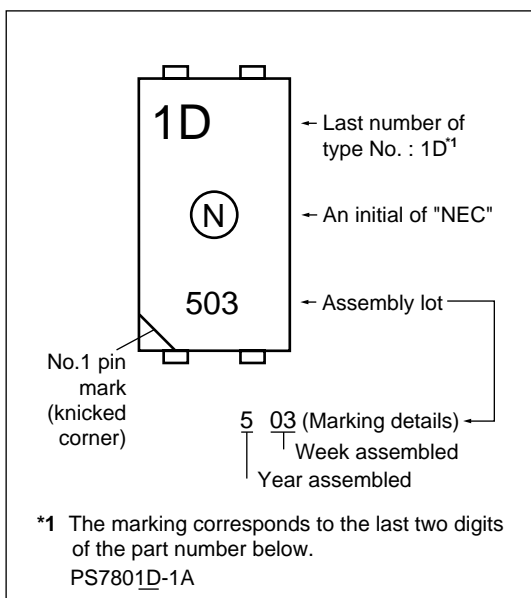
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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS7801D-1A-F3	PS7801D-1A-F3-A	Pb-Free ^{*2}	Embossed Tape 3 500 pcs/reel	UL awaiting approval	PS7801D-1A
PS7801D-1A-F4	PS7801D-1A-F4-A				

*1 For the application of the Safety Standard, following part number should be used.

*2 With regards to terminal solder (the solder contains lead) plated products (conventionally plated), contact your nearby sales office.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I _F	50	mA
	Reverse Voltage	V _R	5.0	V
	Power Dissipation	P _D	50	mW
	Peak Forward Current ^{*1}	I _{FP}	1	A
MOS FET	Break Down Voltage	V _L	40	V
	Continuous Load Current	I _L	120	mA
	Power Dissipation	P _D	250	mW
Isolation Voltage ^{*2}		BV	500	Vr.m.s.
Total Power Dissipation		P _T	300	mW
Operating Ambient Temperature		T _A	-40 to +85	°C
Storage Temperature		T _{stg}	-40 to +100	°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
Pins 1-2 shorted together, 3-4 shorted together.

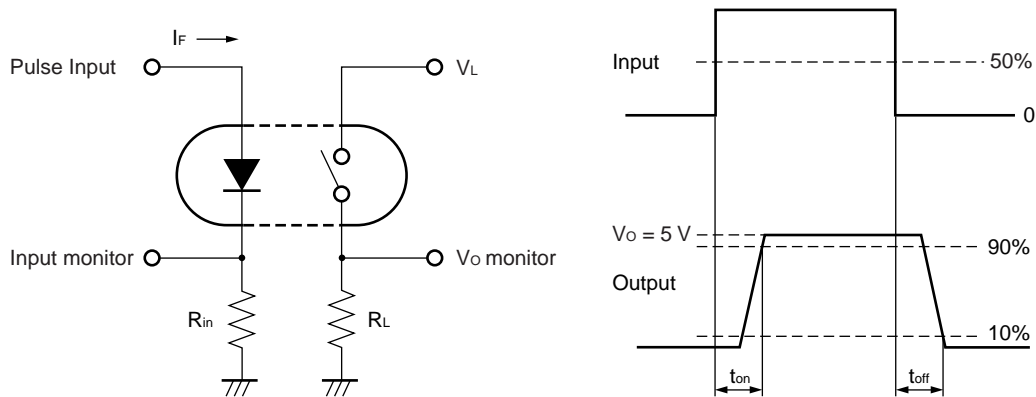
RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I _F	2	5	20	mA
LED Off Voltage	V _F	0		0.5	V

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 5 mA		1.1	1.4	V
	Reverse Current	I _R	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I _{Loff1}	V _D = 35 V			0.3	nA
		I _{Loff2}	V _D = 40 V		0.1	1.0	
	Output Capacitance	C _{out}	V _D = 0 V, f = 1 MHz		0.57	0.85	pF
Coupled	LED On-state Current	I _{Fon}	I _L = 120 mA			2.0	mA
	On-state Resistance	R _{on}	I _F = 5 mA, I _L = 120 mA, t ≤ 10 ms		11.6	16	Ω
	Turn-on Time ^{*1,2}	t _{on}	I _F = 5 mA, V _O = 5 V, R _L = 500 Ω, PW ≥ 10 ms		0.03	0.5	ms
	Turn-off Time ^{*1,2}	t _{off}			0.1	0.5	
	Isolation Resistance	R _{I-O}	V _{I-O} = 0.5 kV _{DC}	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.3		pF

***1 Test Circuit for Switching Time**

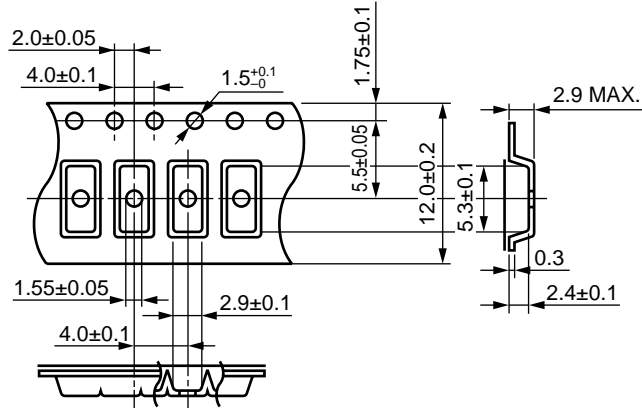


***2** The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

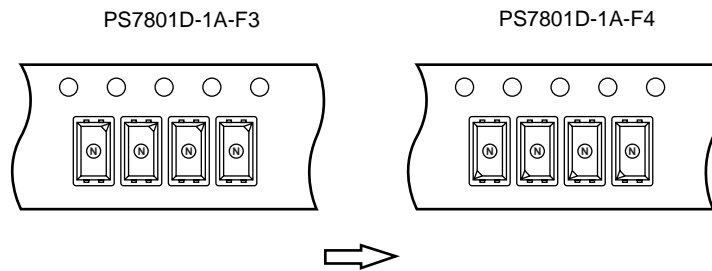
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TAPING SPECIFICATIONS (UNIT: mm)

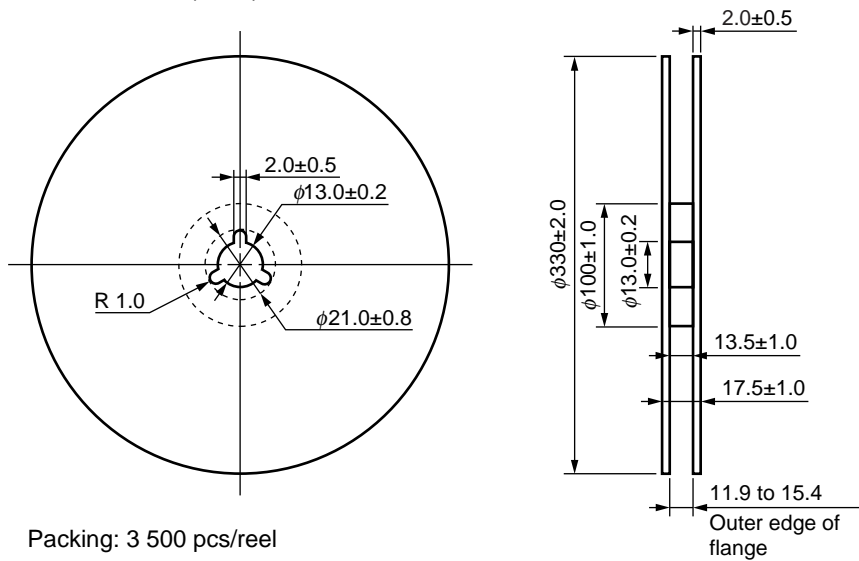
Outline and Dimensions (Tape)



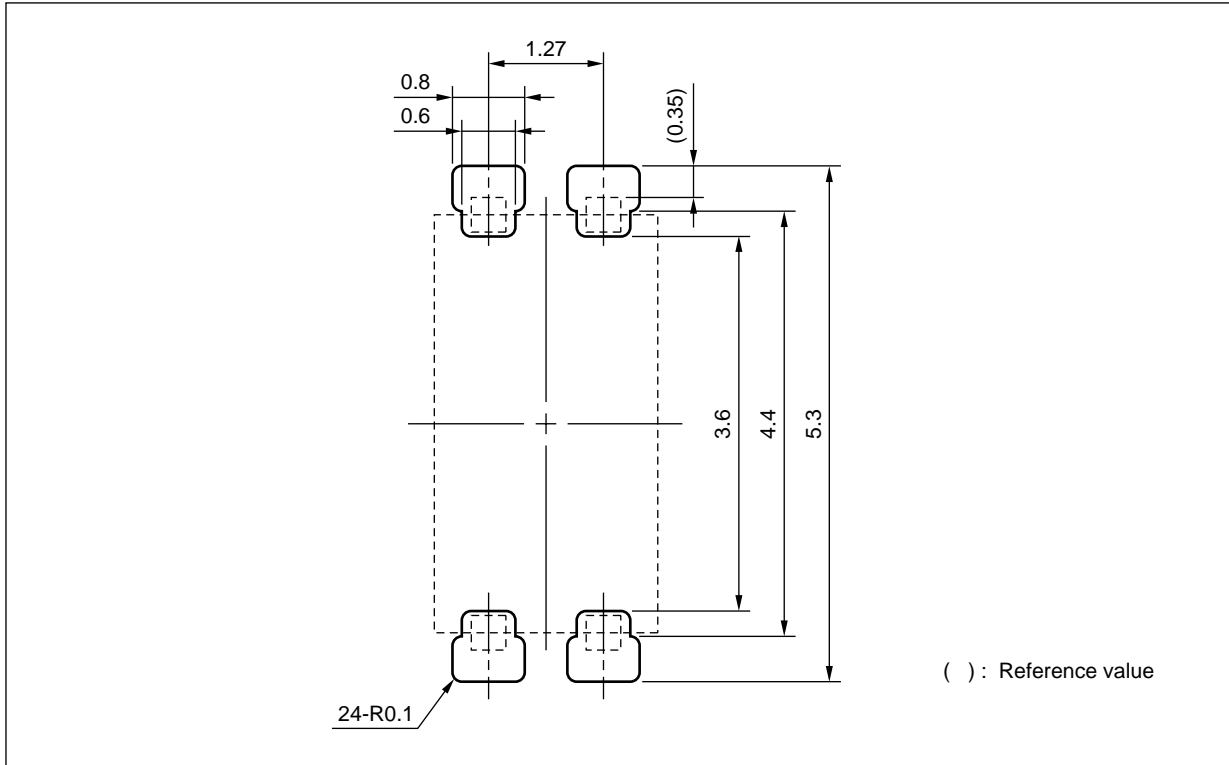
Tape Direction



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



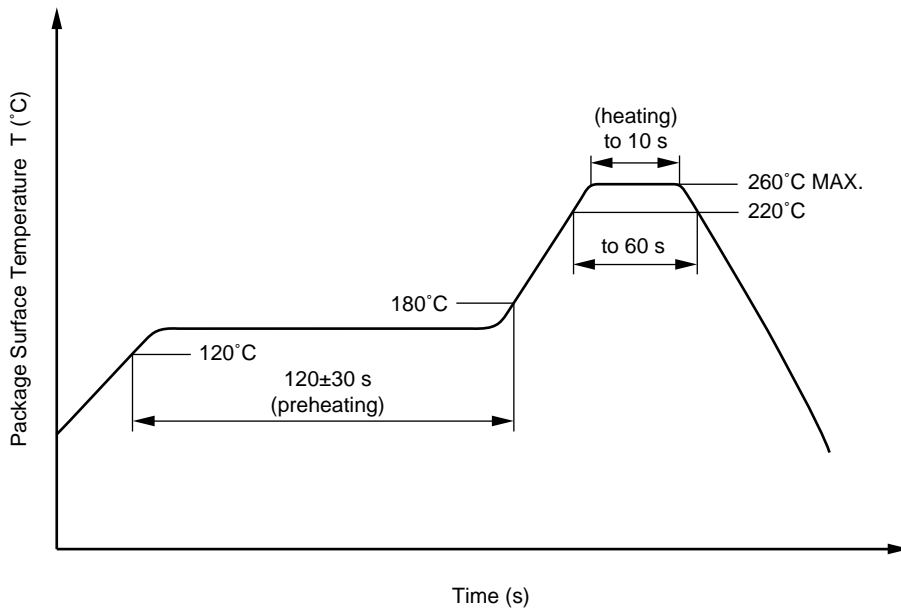
Remark All dimensions in this figure must be evaluated before use.

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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(Note)

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(2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).

M8E 00.4-0110

<p>Caution</p>	<p>GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. <ul style="list-style-type: none"> • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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► **For further information, please contact**

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